

共模磁珠

Ferrite Bead (Bead Array)



特性

Characteristics

低直流电阻

Low DC resistance

阻抗高达200 Ω

Impedance up to 200 Ω

最大电流容量高达41 A

Maximum current capability up to 41 A

应用

Application

供电系统

Power supply systems

对称数据线

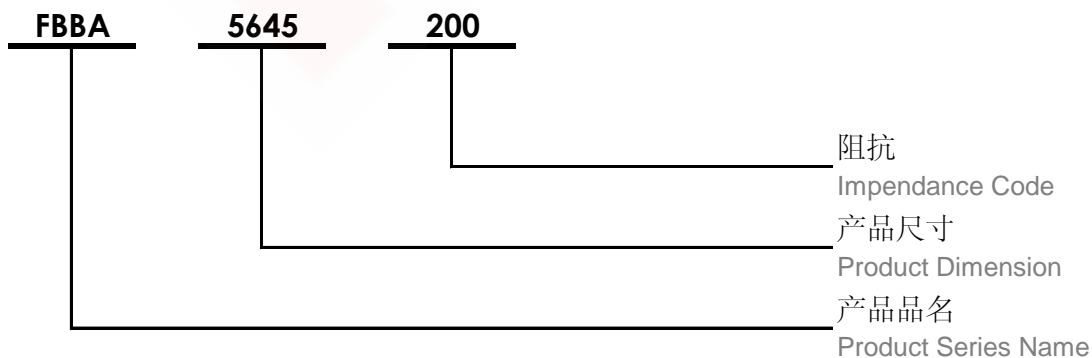
Symmetric data lines

电力电子

Power electronics

产品品名介绍

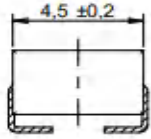
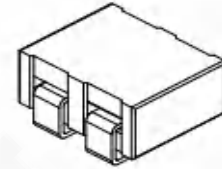
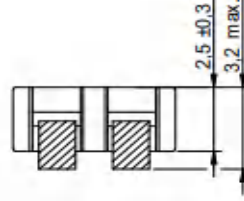
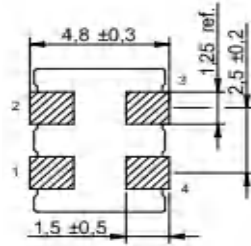
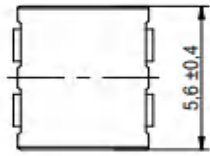
Product Number Structure





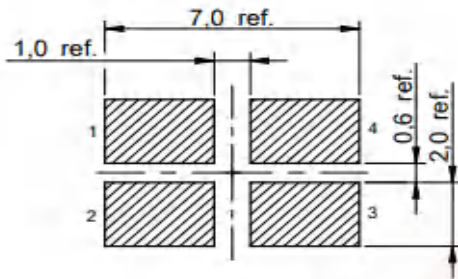
尺寸

Dimension (mm)



焊盘推荐

Land Pattern Recommended (mm)



示意图

Schematics



电性特性

Electrical Properties

型号 Part No.	阻抗 Impedance Z (Ω) ±25%	温升电流 Rated Current I _R 40°C typ. (A)	直流电阻 DC Resistance DCR _{max} (mΩ)	卷盘数量 Taping Reel Qty. pcs
FBBA5645-300	@25 MHz 20.0 @100 MHz 30.0	34.00	3.00	2,000

测试状态

Test Condition

☆ 速率电压: 80V(DC)

Rate Voltage: 80 V(DC)

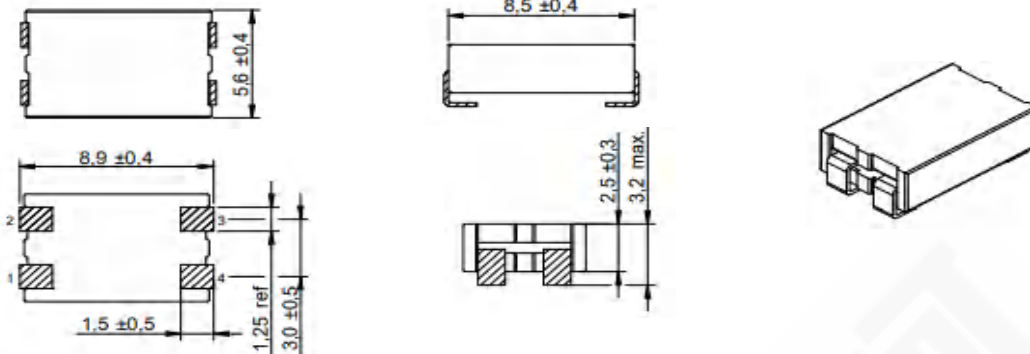
☆ 工作温度: -40°C ~ +125°C

Operating Temperature: -55°C ~ +125°C



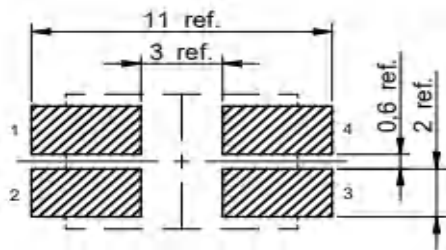
尺寸

Dimension (mm)



焊盘推荐

Land Pattern Recommended (mm)



示意图

Schematics



电性特性

Electrical Properties

型号 Part No.	阻抗 Impedance Z (Ω) ±25%	温升电流 Rated Current I _R 40°C typ. (A)	直流电阻 DC Resistance DCR _{max} (mΩ)	卷盘数量 Taping Reel Qty. pcs
FBBA5685-520	@25 MHz 34.0 @100 MHz 52.0	38.00	3.00	2,400

测试状态

Test Condition

☆ 速率电压: 80V(DC)

Rate Voltage: 80 V(DC)

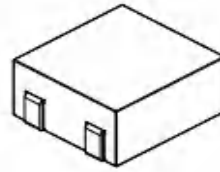
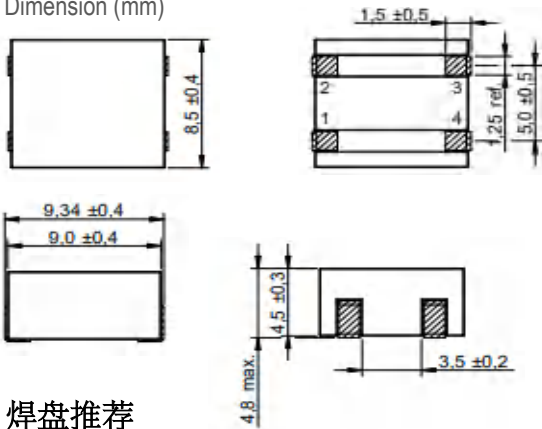
☆ 工作温度: -40°C ~ +125°C

Operating Temperature: -55°C ~ +125°C



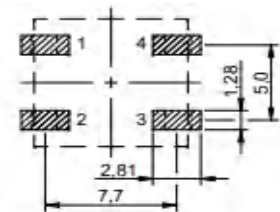
尺寸

Dimension (mm)



焊盘推荐

Land Pattern Recommended (mm)



示意图

Schematics



电性特性

Electrical Properties

型号 Part No.	阻抗 Impedance $Z(\Omega) \pm 25\%$	温升电流 Rated Current $I_R 40^\circ\text{C typ. (A)}$	直流电阻 DC Resistance DCRmax (m Ω)	卷盘数量 Taping Reel Qty. pcs
FBBA8593-830	@25 MHz 54.0 @100 MHz 83.0	41.00	3.00	2,400

测试状态

Test Condition

☆ 速率电压: 80V(DC)

Rate Voltage: 80 V(DC)

☆ 工作温度: $-40^\circ\text{C} \sim +125^\circ\text{C}$

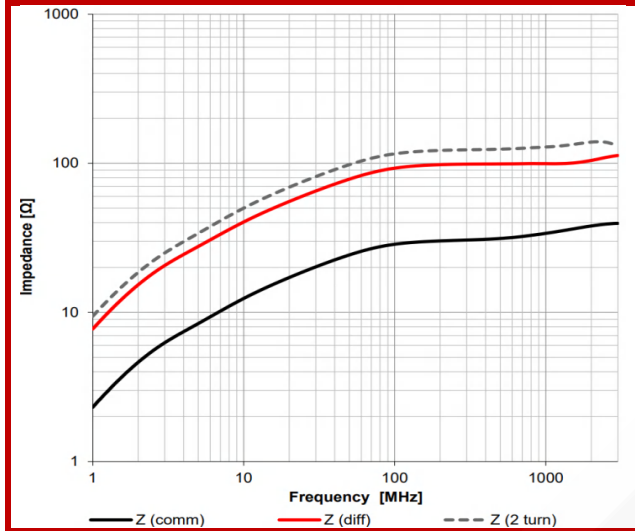
Operating Temperature: $-55^\circ\text{C} \sim +125^\circ\text{C}$



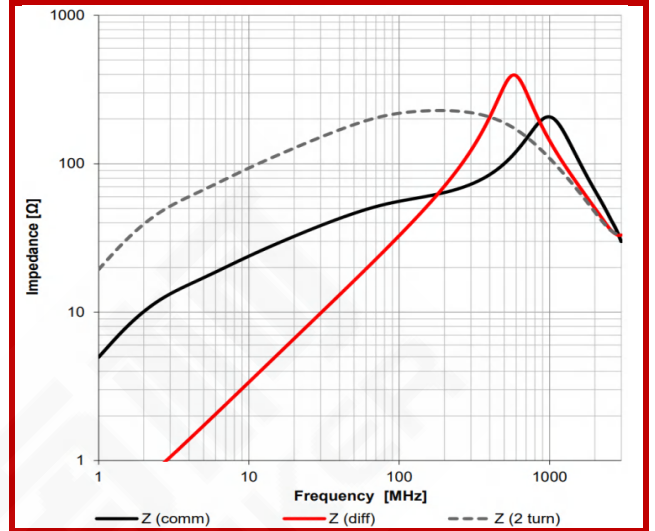
典型阻抗特性

Typical Impedance Characteristics

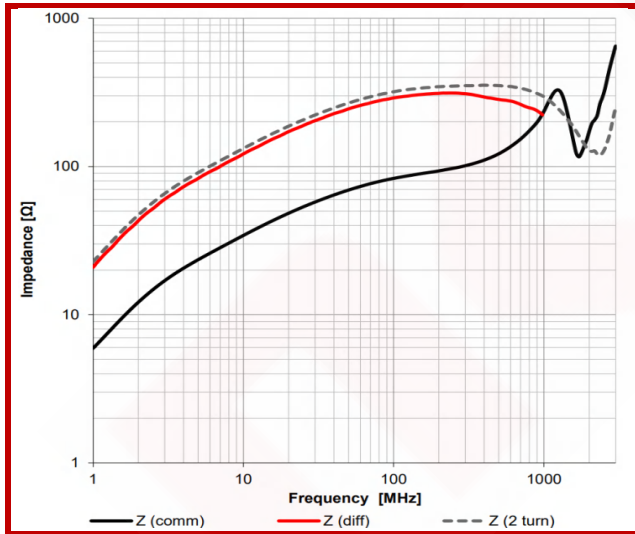
FBBA5645-200



FBBA5685-340



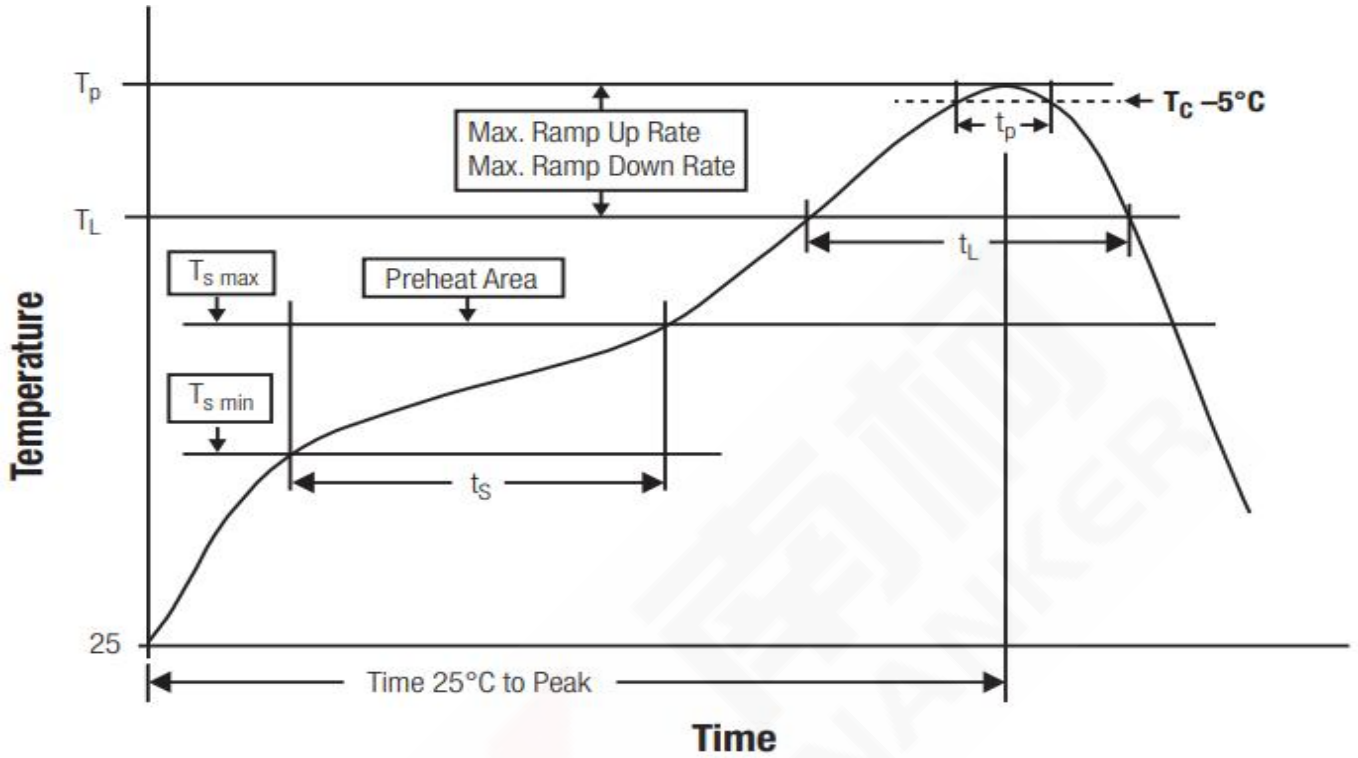
FBBA8593-540





回流焊曲线图

Classification Reflow Profile for SMT Components



封装体峰值温度(Tp)分类

Classification Reflow Soldering Profile:

	封装厚度 Package Thickness	封装体积 Package Volume		
		<350 mm ³	350~2,000 mm ³	>2,000 mm ³
无铅装配 PB-Free Assembly	<1.60mm	260°C	260°C	260°C
	1.60~2.50mm	260°C	250°C	245°C
	>2.50mm	260°C	245°C	245°C

- ◆ 回流焊参照标准 IPC/JEDEC J-STD-020D。
Reflow is refer to standard IPC/JEDEC J-STD-020D.